

# APPLICATION UNDER UNITED STATES PATENT LAWS #13

Atty. Dkt. No. PW 276725  
(M#)

Invention: MULTILAYER BUILD-UP WIRING BOARD

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*Subst Spec*  
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*7/25/02*

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Pillsbury Winthrop LLP

*O.K. to enter*

*1B Patent*  
*4/27/03*

This is a:

- ☐ Provisional Application
- ☐ Regular Utility Application
- ☐ Continuing Application
  - ☒ The contents of the parent are incorporated by reference
- ☐ PCT National Phase Application
- ☐ Design Application
- ☐ Reissue Application
- ☐ Plant Application
- ☐ Substitute Specification
  - Sub. Spec Filed \_\_\_\_\_
  - in App. No. \_\_\_\_\_ / \_\_\_\_\_
- ☒ Marked up Specification re

In App. No. 09/787,321

## SPECIFICATION